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BATOP optoelectronics

Soldered SAM on water cooled copper heat sink with 25.0 mm diameter
SAM-λ-A-τ-4.0-25.0w-c or SAM-λ-A-τ-4.0-25.0w-e

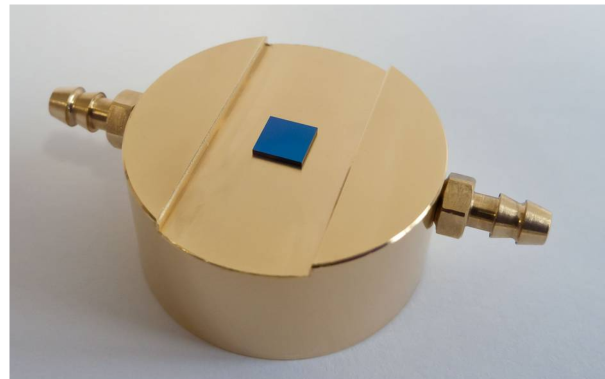
SAM chip area	standard:	4.0 mm x 4.0 mm
Chip thickness	standard:	450 µm
Front side protection	the SAM is protected with a dielectric front layer.	

The SAM chip is soldered on a gold plated, water cooled copper mount with 25.0 mm diameter using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM chip and the mount.

- The ***standard*** mounting position of the SAM is at the center of the heat sink → x = 4.0-25.4w-c.
- ***Optional*** the SAM can be soldered on the edge of the heat sink without extra charges → x = 4.0-25.4w-e.

Edge mounted: SAM-λ-A-4.0-25.0w-e

Centre mounted: SAM-λ-A-4.0-25.0w-c



Back side

This water cooled heat sink comes with a 2 m long water tube with an inner diameter of 3 mm.

Recommended values for cooling water

flow rate:	1000 cm^3/h = 17 cm^3/min
pressure difference	0.03 bar
maximum pressure	1 bar

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